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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



71M6545T/71M6545HT

Energy Meter ICs

General Description

The 71M6545T/71M6545HT metrology processors are based on Maxim Integrated's 4th-generation metering architecture supporting the 71M6xxx series of isolated current sensing products that offer drastic reduction in component count, immunity to magnetic tampering, and unparalleled reliability. The 71M6545T/71M6545HT integrate our Single Converter Technology® with a 22-bit delta sigma ADC, a customizable 32-bit computation engine (CE) for core metrology functions, as well as a user-programmable 8051-compatible application processor (MPU) core with 64KB flash and 5KB RAM.

An external host processor can access metrology functions directly through the SPI interface, or alternatively through the embedded MPU core in applications requiring metrology data capture, storage, and preprocessing within the metrology subsystem. In addition, the devices integrate an RTC, DIO, and UART. A complete array of ICE and development tools, programming libraries, and reference designs enable rapid development and certification of meters that meet all ANSI and IEC electricity metering standards worldwide.

The 71M6545T/71M6545HT operate over the industrial temperature range and come in a 64-pin lead(Pb)-free package.

Applications

- Three-Phase Residential, Commercial, and Industrial Energy Meters

Ordering Information and Typical Operating Circuit appear at end of data sheet.

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Benefits and Features

- SoC Integration and Unique Isolation Technique Reduces BOM Cost Without Sacrificing Performance
 - 0.1% Typical Accuracy Over 2000:1 Current Range
 - Exceeds IEC 62053/ANSI C12.20 Standards
 - Four-Quadrant Metering
 - 46-64Hz Line Frequency Range with the Same Calibration
 - Phase Compensation ($\pm 10^\circ$)
 - Independent 32-Bit Compute Engine
 - 64KB Flash, 5KB RAM
 - Built-In Flash Security
 - SPI Interface to Host with Flash Program Capability
 - Up to Four Pulse Outputs with Pulse Count
 - 8-Bit MPU (80515), Up to 5 MIPS (Optional Use)
 - Full-Speed MPU Clock in Brownout Mode
 - Up to 29 Multifunction DIO Pins
 - Hardware Watchdog Timer (WDT)
 - UART for AMR or Other Communication Duties
 - I²C/MICROWIRE® EEPROM Interface
- Innovative Isolation Technology (Requires Companion 71M6xxx Sensor, also from Maxim Integrated) Eliminates Current Transformers
 - Four Current Sensor Inputs with Selectable Differential Mode
 - Selectable Gain of 1 or 8 for One Current Input to Support Neutral Current Shunt
 - High-Speed Wh/VARh Pulse Outputs with Programmable Width
- Digital Temperature Compensation Improves System Performance
 - Metrology Compensation
 - Accurate RTC for TOU Functions with Automatic Temperature Compensation for Crystal in All Power Modes
- Power Management Extends Battery Life During Power Outages
 - Two Battery-Backup Modes
 - Brownout Mode (BRN)
 - Sleep Mode (SLP)
- Wake-Up on Pin Events and Wake-On Timer
 - 1 μ A in Sleep Mode



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Absolute Maximum Ratings

(All voltages referenced to GNDA.)

Supplies and Ground Pins

V _{V3P3SYS} , V _{V3P3A}	-0.5V to +4.6V
V _{BAT} , V _{BAT_RTC}	-0.5V to +4.6V
GNDD.....	-0.1V to +0.1V

Analog Output Pins

V _{REF}	-10mA to +10mA, -0.5V to (V _{V3P3A} + 0.5V)
V _{DD}	-10mA to +10mA, -0.5V to +3.0V
V _{V3P3D}	-10mA to +10mA, -0.5V to +4.6V

Analog Input Pins

IADC0-7, VADC8-10.....	-10mA to +10mA, -0.5V to (V _{V3P3A} + 0.5V)
XIN, XOUT.....	-10mA to +10mA, -0.5V to +3.0V

DIO Pins

Configured as Digital Inputs-10mA to +10mA, -0.5V to +6.0V
 Configured as Digital Outputs-10mA to +10mA, -0.5V to (V_{V3P3D} + 0.5V)

Digital Pins

Inputs (PB, RESET, RX, ICE_E, TEST).....-10mA to +10mA, -0.5V to +6.0V
 Outputs (TX)..... -10mA to +10mA, -0.5V to (V_{V3P3D} + 0.5V)

Temperature

Operating Junction Temperature (peak, 100ms)..... +140°C
 Operating Junction Temperature (continuous)..... +125°C
 Storage Temperature..... -45°C to +140°C
 Lead Temperature (soldering, 10s) +300°C
 Soldering Temperature (reflow) +260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Electrical Characteristics

(Limits are production tested at T_A = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
RECOMMENDED OPERATING CONDITIONS					
V _{V3P3SYS} and V _{V3P3A} Supply Voltage	Precision metering operation	3.0		3.6	V
V _{BAT}	PLL_FAST = 1	2.65		3.8	V
	PLL_FAST = 0	2.40		3.8	
V _{BAT_RTC}		2.0		3.8	V
Operating Temperature		-40		+85	°C
INPUT LOGIC LEVELS					
Digital High-Level Input Voltage (V _{IH})		2			V
Digital Low-Level Input Voltage (V _{IL})				0.8	V
Input Pullup Current, (I _{IL}) E_RTXT, E_RST, E_TCLK		10		100	µA
Input Pullup Current, (I _{IL}) OPT_RX, OPT_TX		10		100	µA
Input Pullup Current, (I _{IL}) SPI_CSZ (SEGDI036)		10		100	µA
Input Pullup Current, (I _{IL}) Other Digital Inputs		-1		+1	µA
Input Pulldown Current (I _{IH}), ICE_E, RESET, TEST		10		100	µA
Input Pulldown Current, (I _{IH}) Other Digital Inputs		-1		+1	µA

Electrical Characteristics (continued)

(Limits are production tested at $T_A = +25^\circ\text{C}$. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
OUTPUT LOGIC LEVELS					
Digital High-Level Output Voltage (V_{OH})	$I_{LOAD} = 1\text{mA}$	$V_{V3P3D} - 0.4$			V
	$I_{LOAD} = 15\text{mA}$ (Note 1)	$V_{V3P3D} - 0.8$			V
Digital Low-Level Output Voltage (V_{OL})	$I_{LOAD} = 1\text{mA}$	0		0.4	V
	$I_{LOAD} = 15\text{mA}$ (Note 1)	0		0.8	V
BATTERY MONITOR					
Battery Voltage Equation: $3.3 + (\text{BSENSE} - \text{BNOM3P3}) \times 0.0252 + \text{STEMP} \times 2.79\text{E-}5 \text{ V}$					
Measurement Error	$V_{BAT} = 2.0\text{V}$	-3.5		+3.5	%
	$V_{BAT} = 2.5\text{V}$	-3.5		+3.5	
	$V_{BAT} = 3.0\text{V}$	-3.0		+3.0	
	$V_{BAT} = 3.8\text{V}$	-3.0		+3.0	
Input Impedance		260			k Ω
Passivation Current	$I_{BAT}(\text{BCURR} = 1) - I_{BAT}(\text{BCURR} = 0)$	50	100	165	μA
TEMPERATURE MONITOR					
Temperature Measurement Equation		$22.15 + \text{STEMP} \times 0.085 - 0.0023 \times \text{STEMP} \times \frac{[(\text{STEMP}_{T85P} - \text{STEMP}_{T22P}) / (T_{85P} - T_{22P}) - 12.857]}$			$^\circ\text{C}$
Temperature Error (Note 1)	$T_A = +85^\circ\text{C}$	-3.2		+3.2	$^\circ\text{C}$
	$T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$	-2.65		+2.65	
	$T_A = -20^\circ\text{C}$	-3.4		+3.4	
	$T_A = -40^\circ\text{C}$	-3.8		+3.8	
V_{BAT_RTC} Charge per Measurement			2		μC
Duration of Temperature Measurement after TEMP_START			22	40	ms

Electrical Characteristics (continued)

(Limits are production tested at $T_A = +25^\circ\text{C}$. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
SUPPLY CURRENT						
$V_{V3P3A} + V_{V3P3SYS}$ Supply Current (Note 1)	$V_{V3P3A} = V_{V3P3SYS} = 3.3\text{V}$; MPU_DIV = 3 (614kHz MPU clock); PLL_FAST = 1; PRE_E = 0		5.5	6.7	mA	
	PLL_FAST = 0		2.6	3.5		
	PRE_E = 1		5.7	6.9		
	PLL_FAST = 0, PRE_E = 1		2.6	3.6		
Dynamic Current			0.4	0.6	mA/MHz	
V_{BAT} Current	Mission mode	-300		+300	nA	
	Brownout mode		2.4	3.2	mA	
	Sleep mode	-300		+300	nA	
V_{BAT_RTC} Current	Brownout mode		400	650	nA	
	Sleep mode, $T_A \leq 25^\circ\text{C}$		0.7	1.7	μA	
	Sleep mode, $T_A = 85^\circ\text{C}$ (Note 1)		1.5	3.2	μA	
Flash Write Current	Maximum flash write rate		7.1	9.3	mA	
V_{V3P3D} SWITCH						
On-Resistance	$V_{V3P3SYS}$ to V_{V3P3D} , $I_{V3P3D} \leq 1\text{mA}$			11	Ω	
	V_{BAT} to V_{V3P3D} , $I_{V3P3D} \leq 1\text{mA}$			11		
I_{OH}		9			mA	
INTERNAL POWER FAULT COMPARATOR						
Response Time	100mV overdrive, falling	20		200	μs	
	100mV overdrive, rising			200		
Falling Threshold, 3.0V Comparator		2.83	2.93	3.03	V	
Falling Threshold, 2.8V Comparator		2.71	2.81	2.91	V	
Difference between 3.0V and 2.8V comparators		47	136	220	mV	
Falling Threshold, 2.25V Comparator		2.14	2.33	2.51	V	
Falling Threshold, 2.0V Comparator		1.90	2.07	2.23	V	
Difference between 2.25V and 2.0V Comparators		0.15	0.25	0.365	V	
Hysteresis	$T_A = +22^\circ\text{C}$	3.0V comparator	13	45	81	mV
		2.8V comparator	17	42	79	
		2.25V comparator	7	33	71	
		2.0V comparator	4	28	83	

Electrical Characteristics (continued)

(Limits are production tested at $T_A = +25^\circ\text{C}$. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
2.5V REGULATOR					
V_{V2P5} Output Voltage	$V_{V3P3} = 3.0\text{V to } 3.8\text{V}$, $I_{\text{LOAD}} = 0\text{mA}$	2.55	2.65	2.75	V
V_{V2P5} Load Regulation	$V_{\text{BAT}} = 3.3\text{V}$, $V_{V3P3} = 0\text{V}$, $I_{\text{LOAD}} = 0\text{mA to } 1\text{mA}$			40	mV
Dropout Voltage	$I_{\text{LOAD}} = 5\text{mA}$			440	mV
	$I_{\text{LOAD}} = 0\text{mA}$			200	
PSSR	$I_{\text{LOAD}} = 0\text{mA}$		5		mV/V
CRYSTAL OSCILLATOR					
Maximum Output Power to Crystal				1	μW
PLL					
PLL Settling Time	Power-up		3		ms
	PLL_FAST transition, low to high		3		
	PLL_FAST transition, high to low		3		
	Mode transition, sleep to mission		3		
V_{REF}					
V_{REF} Output Voltage	$T_A = +22^\circ\text{C}$	1.193	1.195	1.197	V
V_{REF} Output Impedance	$I_{\text{LOAD}} = -10\mu\text{A to } +10\mu\text{A}$			3.2	$\text{k}\Omega$
V_{REF} Power Supply Sensitivity	$V_{V3P3A} = 3.0\text{V to } 3.6\text{V}$	-1.5		+1.5	mV/V
V_{REF} Temperature Sensitivity (Note 1)		$V_{\text{REF}T} = V_{\text{REF}22} + (T-22)TC_1 + (T-22)^2TC_2$			V
	For 71M6545T	$TC_1 = 151 - 2.77 \times \text{TRIMT}$			$\mu\text{V}/^\circ\text{C}$
	For 71M6545HT	$TC_1 = 33.264 + 0.08 \times \text{TRIMT} + 1.587 \times (\text{TRIMBGB} - \text{TRIMBGD})$			$\mu\text{V}/^\circ\text{C}$
		$TC_2 = -0.528 - 0.00128 \times \text{TRIMT}$			$\mu\text{V}/^\circ\text{C}^2$
V_{REF} Error (Note 1)	71M6545T (-40°C to +85°C)	-40		+40	ppm/°C
	71M6545HT (-40°C to -20°C)	-16		+16	
	71M6545HT (-20°C to +85°C)	-10		+10	
ADC					
Recommended Input Range (All Analog Inputs, Relative to V_{V3P3A})		-250		+250	mV Peak
Recommended Input Range, IADC0-IADC1, Preamp Enabled		-31.25		+31.25	mV Peak
Input Impedance	$f_{\text{IN}} = 65\text{Hz}$	40		100	$\text{k}\Omega$
ADC Gain Error vs. Power Supply	$V_{\text{IN}} = 200\text{mV peak}$, 65Hz, $V_{V3P3A} = 3.0\text{V to } 3.6\text{V}$	-30		+70	ppm/%

Electrical Characteristics (continued)

(Limits are production tested at $T_A = +25^\circ\text{C}$. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Input Offset Voltage	Differential or single-ended modes	-10		+10	mV
THD	250mV peak, 65Hz, 64k points, Blackman-Harris window, FIR_LEN = 2, ADC_DIV = 1, PLL_FAST = 1, MUX_DIV = 2		-93		dB
	20mV peak, 65Hz, 64k points, Blackman-Harris window, FIR_LEN = 2, ADC_DIV = 1, PLL_FAST = 1, MUX_DIV = 2		-90		
LSB Size	FIR_LEN = 2, ADC_DIV = 1, PLL_FAST = 1, MUX_DIV = 2		151		nV
Digital Full Scale	FIR_LEN = 2, ADC_DIV = 1, PLL_FAST = 1, MUX_DIV = 2		$\pm 2,097,152$		LSB
PREAMPLIFIER					
Differential Gain		7.88	7.98	8.08	V/V
Gain Variation vs. Temperature	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (Note 1)	-30	-10	+15	ppm/ $^\circ\text{C}$
Gain Variation vs. V3P3	$V_{V3P3} = 2.97\text{V}$ to 3.63V (Note 1)	-100		+100	ppm/%
Phase Shift	(Note 1)	+10		+22	m°
Preamp Input Current		3	6	9	μA
THD, Preamp + ADC	$V_{IN} = 30\text{mV}$		-88		dB
	$V_{IN} = 15\text{mV}$		-88		
Preamp Input Offset Voltage	$I_{ADC0} = I_{ADC1} = V_{V3P3} + 30\text{mV}$		-0.63		mV
	$I_{ADC0} = I_{ADC1} = V_{V3P3} + 15\text{mV}$		-0.57		
	$I_{ADC0} = I_{ADC1} = V_{V3P3}$		-0.56		
	$I_{ADC0} = I_{ADC1} = V_{V3P3} - 15\text{mV}$		-0.56		
	$I_{ADC0} = I_{ADC1} = V_{V3P3} - 30\text{mV}$		-0.55		
Phase Shift Over Temperature	(Note 1)	-0.03		+0.03	m°/C
FLASH MEMORY					
Endurance		20,000			Cycles
Data Retention	$T_A = +25^\circ\text{C}$	100			Years
Byte Writes Between Erase Operations				2	Cycles
Write Time, per Byte	Per 2 bytes if using SPI			50	μs
Page Erase Time				22	ms
Mass Erase Time				22	ms

Electrical Characteristics (continued)

(Limits are production tested at $T_A = +25^\circ\text{C}$. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
SPI					
Data-to-Clock Setup Time		10			ns
Data Hold Time From Clock		10			ns
Output Delay, Clock to Data				40	ns
CS-to-Clock Setup Time		10			ns
Hold Time, CS to Clock		15			ns
Clock High Period		40			ns
Clock Low Period		40			ns
Clock Frequency (as a Multiple of CPU Frequency)				2.0	MHz/MHz
Space Between SPI Transactions		4.5			CPU Cycles
EEPROM INTERFACE					
I ² C SCL Frequency	MPU clock = 4.9MHz, using interrupts		310		kHz
	MPU clock = 4.9MHz, bit-banging DIO2-DIO3		100		
3-Wire Write Clock Frequency	MPU clock = 4.9MHz, PLL_FAST = 0		160		kHz
	MPU clock = 4.9MHz, PLL_FAST = 1		490		
RESET					
Reset Pulse Width	(Note 1)	5			μs
Reset Pulse Fall Time	(Note 1)			1	μs
INTERNAL CALENDAR					
Year Date Range		2000		2255	Years

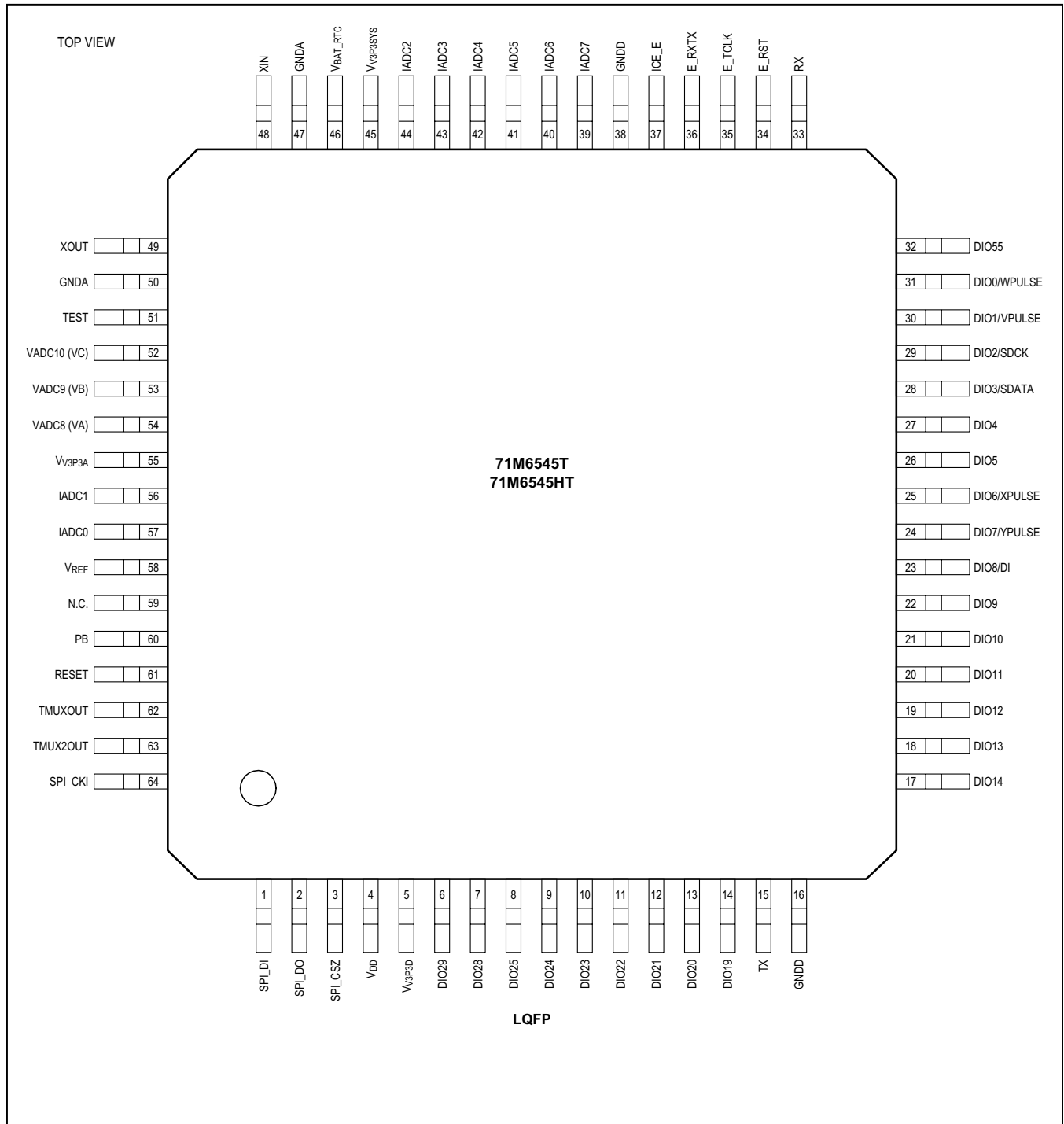
Recommended External Components

NAME	FROM	TO	FUNCTION	VALUE	UNITS
C1	V _{V3P3A}	GNDA	Bypass capacitor for 3.3V supply	$\geq 0.1 \pm 20\%$	μF
C2	V _{V3P3D}	GNDD	Bypass capacitor for 3.3V output	$0.1 \pm 20\%$	μF
CSYS	V _{V3P3SYS}	GNDD	Bypass capacitor for V _{V3P3SYS}	$\geq 1.0 \pm 30\%$	μF
CVDD	V _{DD}	GNDD	Bypass capacitor for V _{DD}	$0.1 \pm 20\%$	μF
XTAL	XIN	XOUT	32.768 kHz crystal; electrically similar to ECS .327-12.5-17X, Vishay XT26T or Suntu SCP6–32.768kHz TR (load capacitance 12.5pF)	32.768	kHz
CXS (Note 2)	XIN	GNDA	Load capacitor values for crystal depend on crystal specifications and board parasitics. Nominal values are based on 3pF allowance for the sum of board capacitance and chip capacitance.	$22 \pm 10\%$	pF
CXL (Note 2)	XOUT	GNDA		$22 \pm 10\%$	pF

Note 1: Parameter not tested in production, guaranteed by design to six-sigma.

Note 2: If the capacitor values of CXS = 15pF and CXL = 10pF have already been installed, then changing the CXL value to 33pF and leaving CXS = 15pF would minimize rework.

Pin Configuration



Pin Descriptions

PIN	NAME	TYPE	CIRCUIT	FUNCTION
POWER AND GROUND PINS				
47, 50	GNDA	P	—	Analog Ground. This pin should be connected directly to the ground plane.
16, 38	GNDD	P	—	Digital Ground. This pin should be connected directly to the ground plane.
55	V _{V3P3A}	P	—	Analog Power Supply. A 3.3V power supply should be connected to this pin. V _{V3P3A} must be the same voltage as V _{V3P3SYS} .
45	V _{V3P3SYS}	P	—	System 3.3V supply. This pin should be connected to a 3.3V power supply.
5	V _{V3P3D}	O	13	Auxiliary Voltage Output of the Chip. In mission mode, this pin is connected to V _{V3P3SYS} by the internal selection switch. In BRN mode, it is internally connected to V _{BAT} . V _{V3P3D} is floating in LCD and sleep mode. A 0.1μF bypass capacitor to ground must be connected to this pin.
4	V _{DD}	O	—	Output of the 2.5V Regulator. This pin is powered in MSN and BRN modes. A 0.1μF bypass capacitor to ground should be connected to this pin.
46	V _{BAT_RTC}	P	12	RTC and Oscillator Power Supply. A battery or super capacitor is to be connected between V _{BAT} and GNDD. If no battery is used, connect V _{BAT_RTC} to V _{V3P3SYS} .
ANALOG PINS				
57, 56	IADC0 IADC1	I	6	Differential or Single-Ended Line Current Sense Inputs. These pins are voltage inputs to the internal A/D converter. Typically, they are connected to the outputs of current sensors. Unused pins must be tied to V _{V3P3A} . Pins IADC2-IADC3, IADC4-IADC5 and IADC6-IADC7 may be configured for communication with the remote sensor interface (71M6x03).
44, 43	IADC2 IADC3			
42, 41	IADC4 IADC5			
40, 39	IADC6 IADC7			
54, 53, 52	VADC8 (VA), VADC9 (VB), VADC10 (VC)	I	6	Line Voltage Sense Inputs. These pins are voltage inputs to the internal A/D converter. Typically, they are connected to the outputs of resistor-dividers. Unused pins must be tied to V _{V3P3A} .
58	V _{REF}	O	9	Voltage Reference for the ADC. This pin should be left unconnected (floating).
48	XIN	I	8	Crystal Inputs. A 32.768kHz crystal should be connected across these pins. Typically, a 22pF capacitor is also connected from XIN to GNDA and a 22pF capacitor is connected from XOUT to GNDA. It is important to minimize the capacitance between these pins. See the crystal manufacturer data sheet for details. If an external clock is used, a 150mV _{p-p} clock signal should be applied to XIN, and XOUT should be left unconnected.
49	XOUT	O		

Pin Descriptions (continued)

PIN	NAME	TYPE	CIRCUIT	FUNCTION
DIGITAL PINS				
31	DIO0/WPULSE	I/O	3	Multiple-Use Pins. Alternative functions with proper selection of associated I/O RAM registers are: DIO0 = WPULSE DIO1 = VPULSE DIO2 = SDCK DIO3 = SDATA DIO4 = XPULSE DIO6 = YPULSE DIO7 = DI DIO8 = RX3 DIO16 = TX3 Unused pins must be configured as outputs or terminated to V3P3/GNDD.
30	DIO1/VPULSE			
29	DIO2/SDCK			
28	DIO3/SDATA			
27	DIO4			
26	DIO5			
25	DIO6/XPULSE			
24	DIO7/YPULSE			
23	DIO8/DI			
22-17	DIO[9:14]			
14-8	DIO[19:25]			
7-6	DIO[28:29]			
3	SPI_CSZ	I/O	3	SPI Interface
2	SPI_DO			
1	SPI_DI			
64	SPI_CK1			
32	DIO55	I/O	3	DIO
36	E_RXTX	I/O	1	Emulator Port Pins
34	E_RST			
35	E_TCLK	O	4	
37	ICE_E	I	2	ICE Enable. For production units, this pin should be pulled to GND to disable the emulator port.
62	TMUXOUT	O	4, 5	Multiplexer/Clock Output
63	TMUX2OUT			
61	RESET	I	2	Chip Reset. This input pin is used to reset the chip into a known state. For normal operation, this pin is pulled low. To reset the chip, this pin should be pulled high. This pin has an internal 30FA (nominal) current source pulldown. No external reset circuitry is necessary.
33	RX	I	3	UART Input. If this pin is unused it must be terminated to V _{V3P3D} or GNDD.
15	TX	O	4	UART Output
51	TEST	I	7	Enables Production Test. This pin must be grounded in normal operation.
60	PB	I	3	Pushbutton Input. This pin must be at GNDD when not active or unused. A rising edge sets the WF_PB flag. It also causes the part to wake up if it is in SLP mode. PB does not have an internal pullup or pulldown resistor.
59	N.C.	N.C.	—	No Connection. Do not connect these pins.

I = Input, O = Output, P = Power

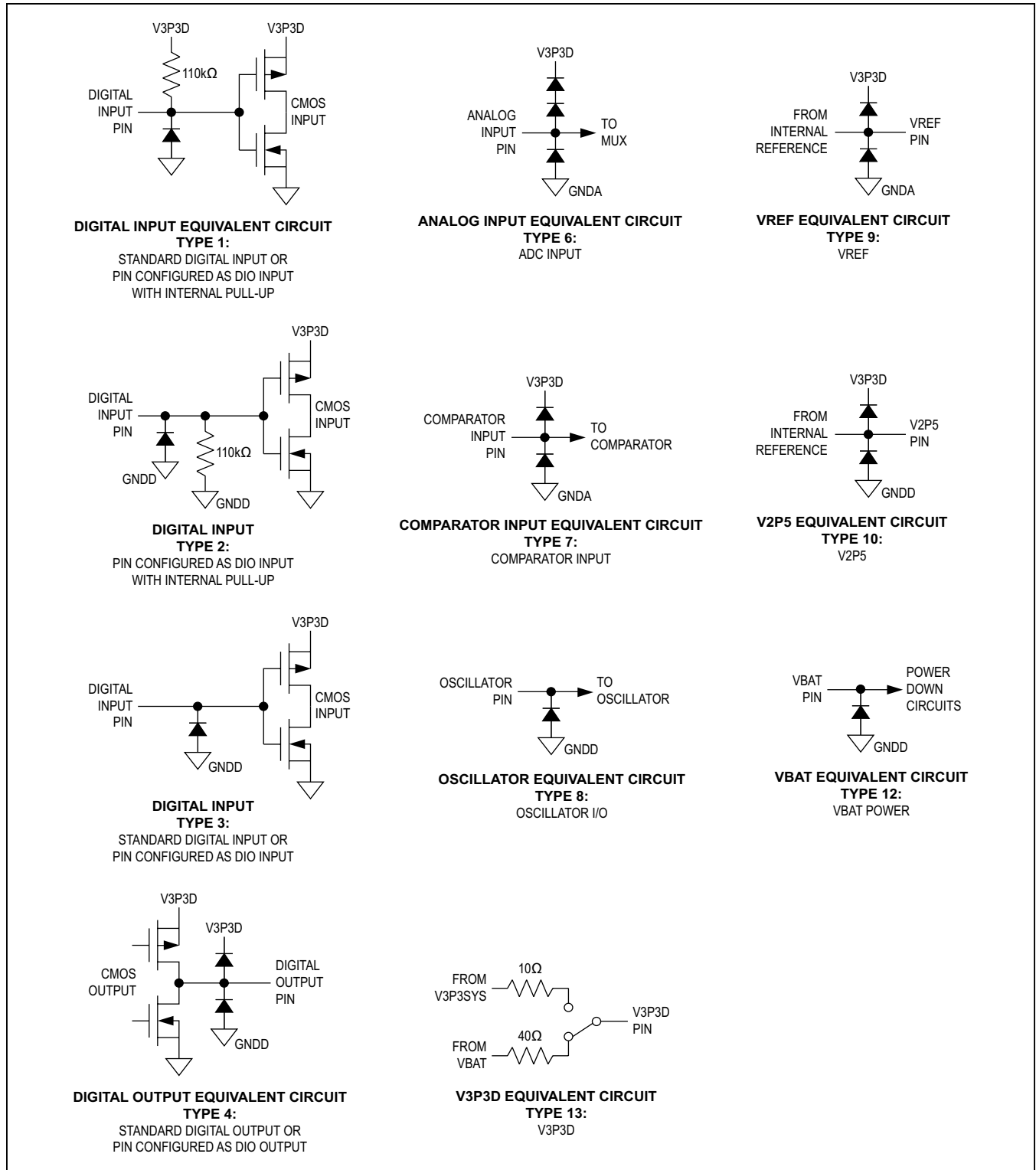
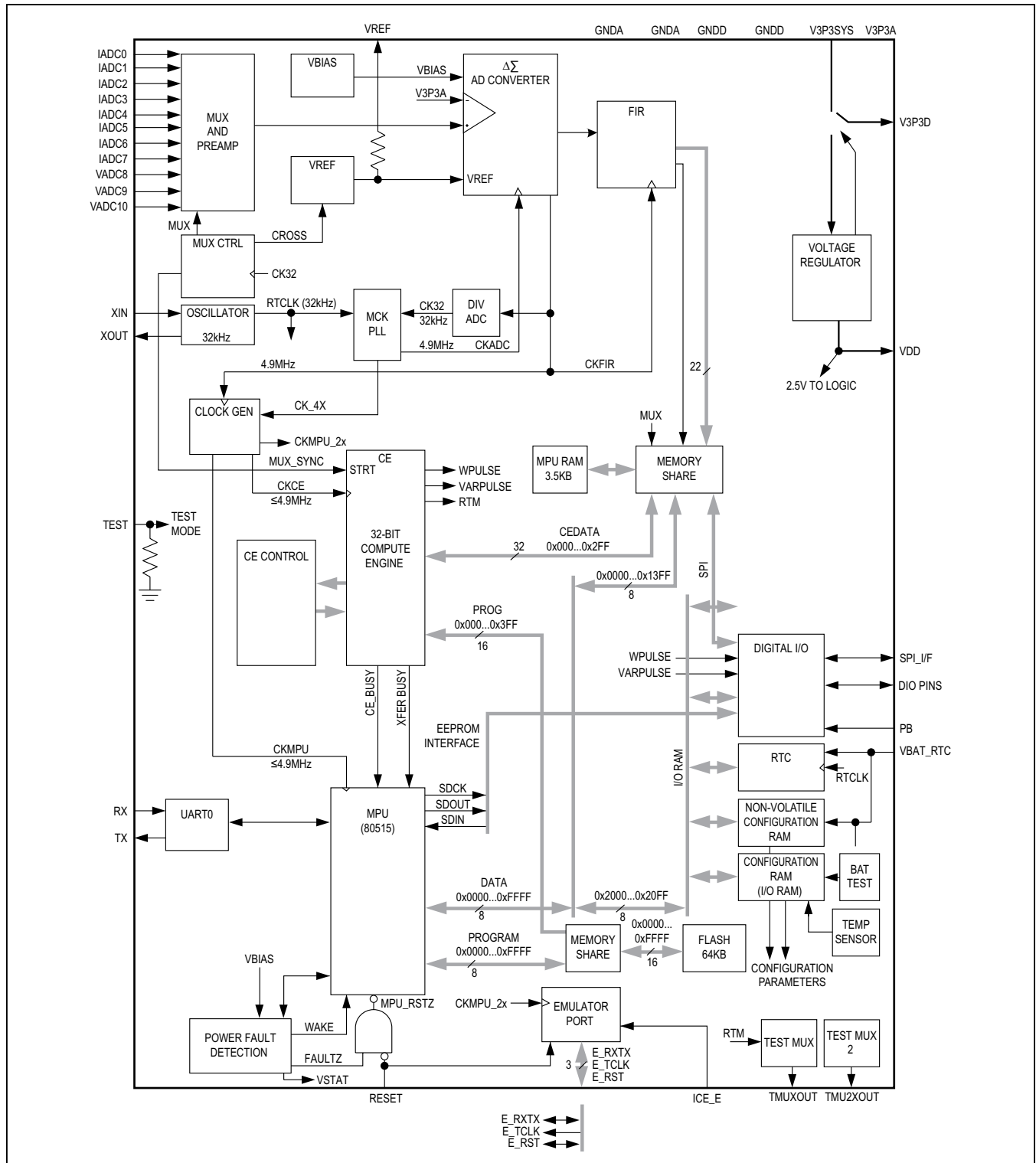


Figure 1. I/O Equivalent Circuits

Block Diagram



Hardware Description

The 71M6545T/HT single-chip energy meter ICs integrate all primary functional blocks required to implement a solid-state residential electricity meter. Included on the chip are the following:

- An analog front-end (AFE) featuring a 22-bit second-order sigma-delta ADC
- An independent 32-bit digital computation engine (CE) to implement DSP functions
- An 8051-compatible microprocessor (MPU) which executes one instruction per clock cycle (80515)
- A precision voltage reference (V_{REF})
- A temperature sensor for digital temperature compensation:
 - Metrology digital temperature compensation (MPU)
 - Automatic RTC digital temperature compensation operational in all power states
- RAM and flash memory
- A real-time clock (RTC)
- A variety of I/O pins
- A power-failure interrupt
- A zero-crossing interrupt
- Selectable current sensor interfaces for locally-connected sensors as well as isolated sensors (i.e., using the 71M6x03 companion IC with a shunt resistor sensor)
- Resistive shunt and current transformers are supported

Resistive shunts and current transformer (CT) current sensors are supported. Resistive shunt current sensors may be connected directly to the 71M654xT device or isolated using a companion 71M6x03 isolator IC in order to implement a variety of metering configurations. An inexpensive, small pulse transformer is used to isolate the 71M6x03 isolated sensor from the 71M654xT. The 71M654xT performs digital communications bidirectionally with the 71M6x03 and also provides power to the 71M6x03 through the isolating pulse transformer. Isolated (remote) shunt current sensors are connected to the differential input of the 71M6x03. Included on the 71M6x03 companion isolator chip are:

- Digital isolation communications interface
- An analog front-end (AFE)
- A precision voltage reference (V_{REF})
- A temperature sensor (for digital temperature compensation)

- A fully differential shunt resistor sensor input
- A preamplifier to optimize shunt current sensor performance
- Isolated power circuitry obtains dc power from pulses sent by the 71M654xT

In a typical application, the 32-bit compute engine (CE) of the 71M654xT sequentially processes the samples from the voltage inputs on analog input pins and from the external 71M6x03 isolated sensors and performs calculations to measure active energy (Wh) and reactive energy (VARh), as well as A²h, and V²h for four-quadrant metering. These measurements are then accessed by the MPU, processed further and output using the peripheral devices available to the MPU.

In addition to advanced measurement functions, the clock function allows the 71M6545T/HT to record time-of-use (TOU) metering information for multi-rate applications and to time-stamp tamper or other events.

In addition to the temperature-trimmed ultra-precision voltage reference, the on-chip digital temperature compensation mechanism includes a temperature sensor and associated controls for correction of unwanted temperature effects on measurement and RTC accuracy, e.g., to meet the requirements of ANSI and IEC standards. Temperature-dependent external components such as crystal oscillator, resistive shunts, current transformers (CTs) and their corresponding signal conditioning circuits can be characterized and their correction factors can be programmed to produce electricity meters with exceptional accuracy over the industrial temperature range.

See the [Block Diagram](#).

Analog Front-End (AFE)

The AFE functions as a data acquisition system, controlled by the MPU. When used with locally connected sensors, as shown in [Figure 2](#), the analog input signals (IADC0-IADC7, VADC8-VADC10) are multiplexed to the ADC input and sampled by the ADC.

The ADC output is decimated by the FIR filter and stored in CE RAM where it can be accessed and processed by the CE.

When remote isolated sensors are connected to the 71M6545T/HT using 71M6x03 remote sensor interfaces, the input multiplexer is bypassed. Instead, the extracted modulator bit stream is passed directly to a dedicated decimation filter. The output of the decimation filter is then directly stored in the appropriate CE RAM location without making use of a multiplexer cycle.

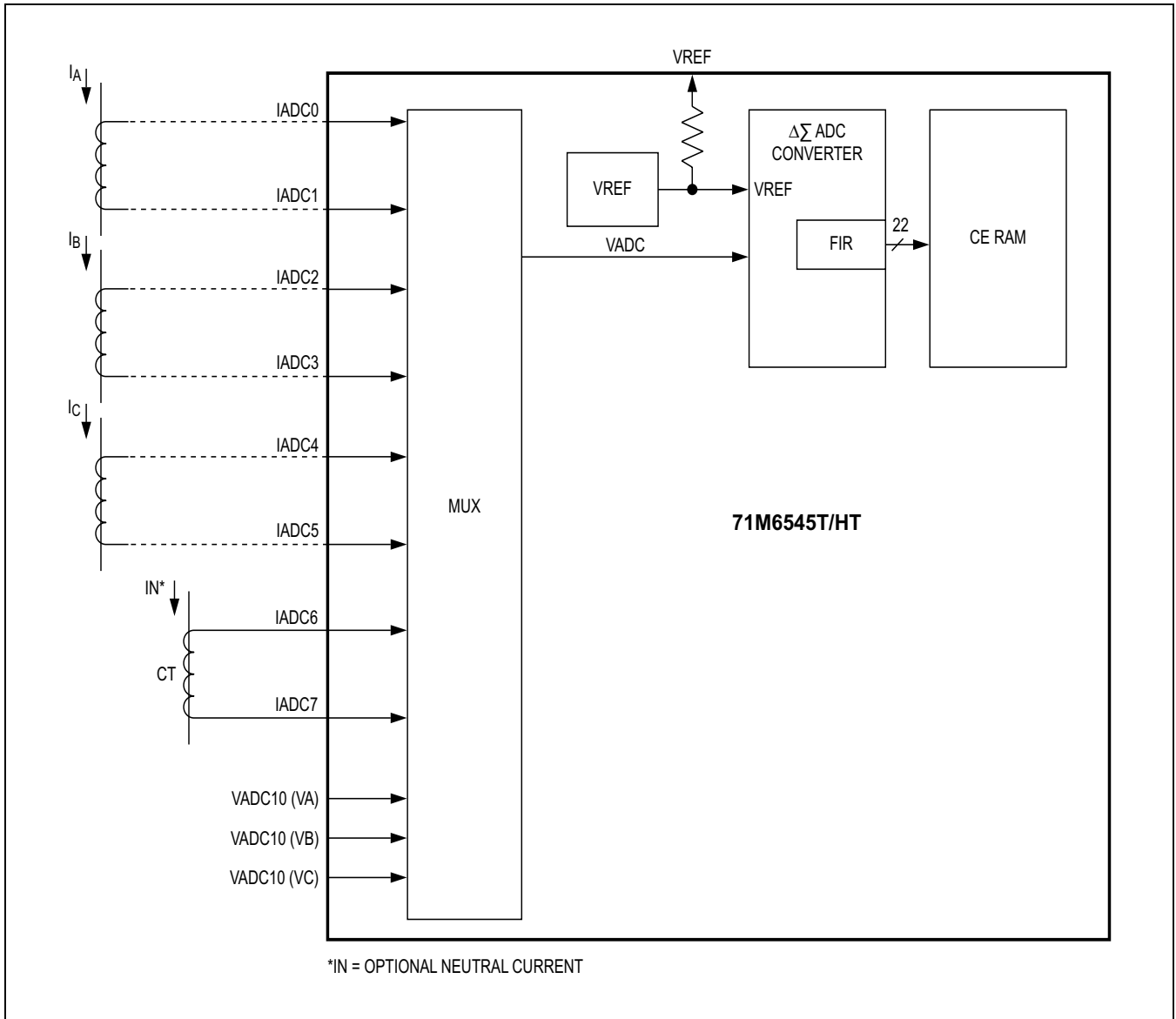


Figure 2. 71M6545T/HT Operating with Local Sensors

Signal Input Pins

The 71M6545T/HT features eleven ADC inputs.

IADC0-IADC7 are intended for use as current sensor inputs. These eight current sensor inputs can be configured as four single-ended inputs, or (more frequently) can be paired to form four differential inputs. For best performance, it is recommended to configure the current sensor inputs as differential inputs. The first differential input (IADC0-IADC1) features a preamplifier with a selectable gain of 1 or 8, and is intended for direct connection to a shunt resistor sensor, and can also be used with a current transformer (CT). The remaining differential pairs may be used with CTs, or may be enabled to interface to a remote 71M6x03 isolated current sensor providing isolation for a shunt resistor sensor using a low cost pulse transformer.

The remaining inputs (VADC8-VADC10) are single-ended and sense line voltage. These single-ended inputs are referenced to the V_{V3P3A} pin.

All analog signal input pins measure voltage. In the case of shunt current sensors, currents are sensed as a voltage drop in the shunt resistor sensor. Referring to Figure 2, shunt sensors can be connected directly to the 71M654xT (referred to as a 'local' shunt sensor) or connected through an isolated 71M6x03 (referred to as a 'remote' shunt sensor) (Figure 3). In the case of current transformers, the current is measured as a voltage across a burden resistor that is connected to the secondary winding of the CT. Meanwhile, line voltages are sensed through resistive voltage dividers.

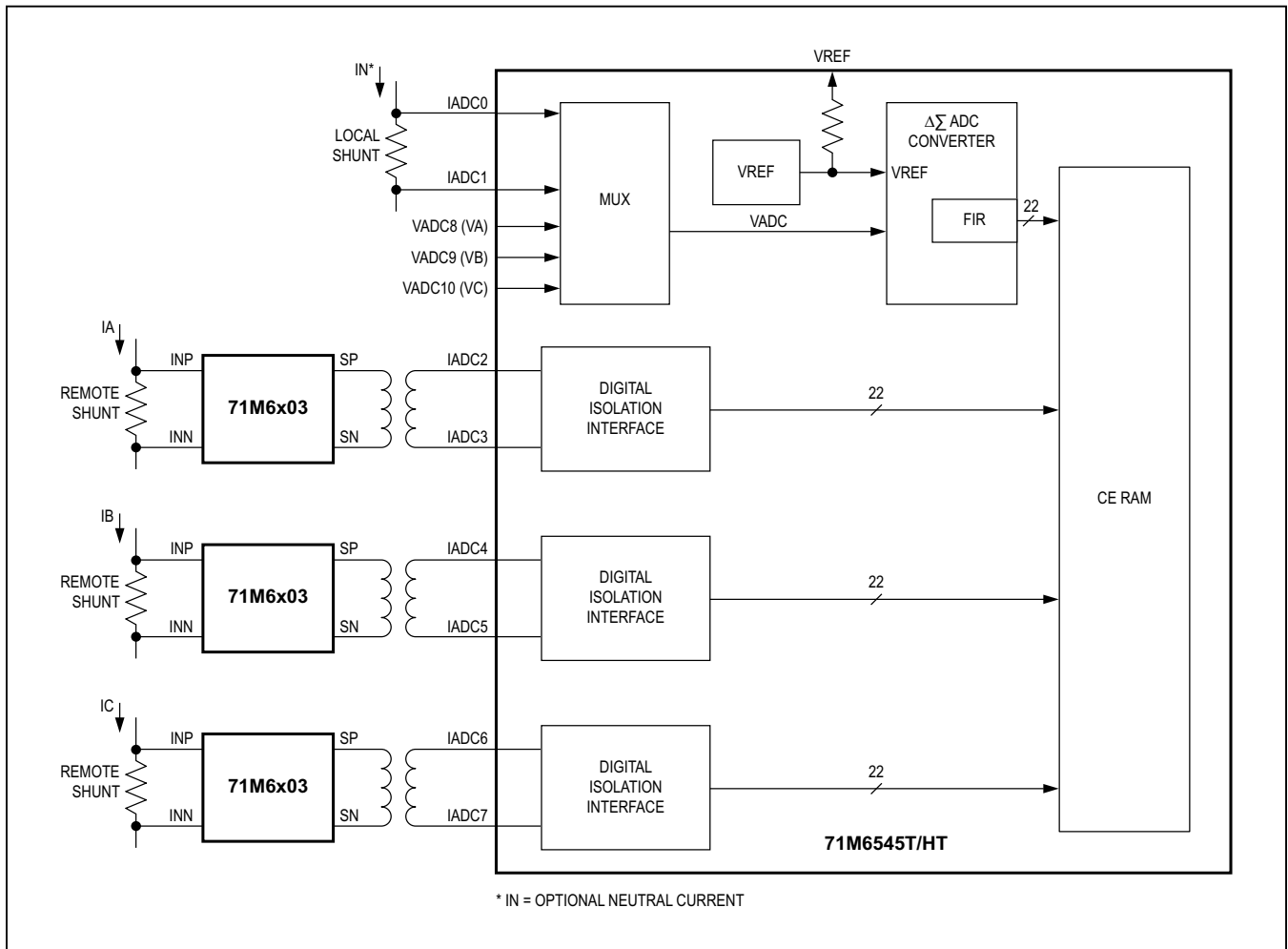


Figure 3. 71M6545T/HT Operating with Remote Sensor for Neutral Current

Pins IADC0-IADC1 can be programmed individually to be differential or single-ended. For most applications IADC0-IADC1 are configured as a differential input to work with a shunt or CT directly interfaced to the IADC0-IADC1 differential input with the appropriate external signal conditioning components.

The performance of the IADC0-IADC1 pins can be enhanced by enabling a preamplifier with a fixed gain of 8. When the PRE_E bit = 1, IADC0-IADC1 become the inputs to the 8x preamplifier, and the output of this amplifier is supplied to the multiplexer. The 8x amplification is useful when current sensors with low sensitivity, such as shunt resistors, are used. With PRE_E set, the IADC0-IADC1 input signal amplitude is restricted to 31.25 mV peak.

When shunt resistors are used as current sense elements on all current inputs, the IADC0-IADC1 pins are configured for differential mode to interface to a local shunt by setting the DIFFA_E control bit. Meanwhile, the IADC2-IADC7 pins are re-configured as digital balanced pair to communicate with a 71M6x03 isolated sensor interface by setting the RMT_E control bit. The 71M6x03 communicates with the 71M654xT using a bidirectional digital data stream through an isolating low-cost pulse transformer. The 71M654xT also supplies power to the 71M6x03 through the isolating transformer.

When using current transformers the IADC2-IADC7 pins are configured as local analog inputs (RMT_E = 0). The IADC0-IADC1 pins cannot be configured as a remote sensor interface.

Input Multiplexer

When operating with local sensors, the input multiplexer sequentially applies the input signals from the analog input pins to the input of the ADC. One complete sampling sequence is called a multiplexer frame. The multiplexer of the 71M6545T/HT can select up to seven input signals (three voltage inputs and four current inputs) per multiplexer frame. The multiplexer always starts at state 1 and proceeds until as many states as determined by MUX_DIV[3:0] have been converted.

The 71M6545T/HT requires CE code that is written for the specific application. Moreover, each CE code requires specific AFE and MUX settings in order to function properly. Contact Maxim Integrated for specific information about alternative CE codes.

For a polyphase configuration with neutral current sensing using shunt resistor current sensors and the 71M6xx3 isolated sensors, as shown in [Figure 3](#), the IADC0-IADC1 input must be configured as a differential input, to be connected to a local shunt. The local shunt connected to the IADC0-IADC1 input is used to sense the Neutral current. The voltage sensors (VADC8-VADC10) are also directly connected to the 71M6545T/HT and are also routed through the multiplexer. Meanwhile, the IADC2-IADC7 current inputs are configured as remote sensor digital interfaces and the corresponding samples are not routed through the multiplexer.

For a polyphase configuration with optional neutral current sensing using Current Transformer (CTs) sensors, all four current sensor inputs must be configured as differential inputs. IADC2-IADC3 is connected to phase A, IADC4-IADC5 is connected to phase B, and IADC6-IADC7 is connected to phase C. The IADC0-IADC1 current sensor input is optionally used to sense the Neutral current for anti-tampering purposes. The voltage sensors (VADC8-VADC10), typically resistive dividers, are directly connected to the 71M6545T/HT. No 71M6xx3 isolated sensors are used in this configuration and all signals are routed through the multiplexer.

The multiplexer sequence shown in [Figure 4](#) corresponds to the configuration shown in [Figure 3](#). The frame duration is 13 CK32 cycles (where CK32 = 32,768Hz), therefore, the resulting sample rate is $32,768\text{Hz}/13 = 2,520.6\text{Hz}$. Note that [Figure 4](#) only shows the currents that pass through the 71M6545T/HT multiplexer, and does not show the currents that are copied directly into CE RAM from the remote sensors (see [Figure 3](#)), which are sampled during the second half of the multiplexer frame. The two unused conversion slots shown are necessary to produce the desired 2,520.6Hz sample rate.

The multiplexer sequence shown in [Figure 5](#) corresponds to the CT configuration shown in [Figure 2](#). Since in this case all current sensors are locally connected to the 71M6545T/HT, all currents are routed through the multiplexer, as seen in [Figure 2](#). For this multiplexer sequence, the frame duration is 15 CK32 cycles (where CK32 = 32,768Hz), therefore, the resulting sample rate is $32,768\text{Hz}/15 = 2,184.5\text{Hz}$.

Delay Compensation

When measuring the energy of a phase (i.e., Wh and VARh) in a service, the voltage and current for that phase must be sampled at the same instant. Otherwise, the phase difference, Φ , introduces errors.

$$\phi = \frac{t_{\text{delay}}}{T} \cdot 360^\circ = t_{\text{delay}} \cdot f \cdot 360^\circ$$

Where f is the frequency of the input signal, $T = 1/f$ and t_{delay} is the sampling delay between current and voltage. Traditionally, sampling is accomplished by using two A/D converters per phase (one for voltage and the other one

for current) controlled to sample simultaneously. Our Single Converter Technology, however, exploits the 32-bit signal processing capability of its CE to implement “constant delay” allpass filters. The allpass filter corrects for the conversion time difference between the voltage and the corresponding current samples that are obtained with a single multiplexed A/D converter.

The “constant delay” allpass filter provides a broad-band delay $360^\circ - \theta$, which is precisely matched to the difference in sample time between the voltage and the current of a given phase. This digital filter does not affect the amplitude of the signal, but provides a precisely controlled phase response.

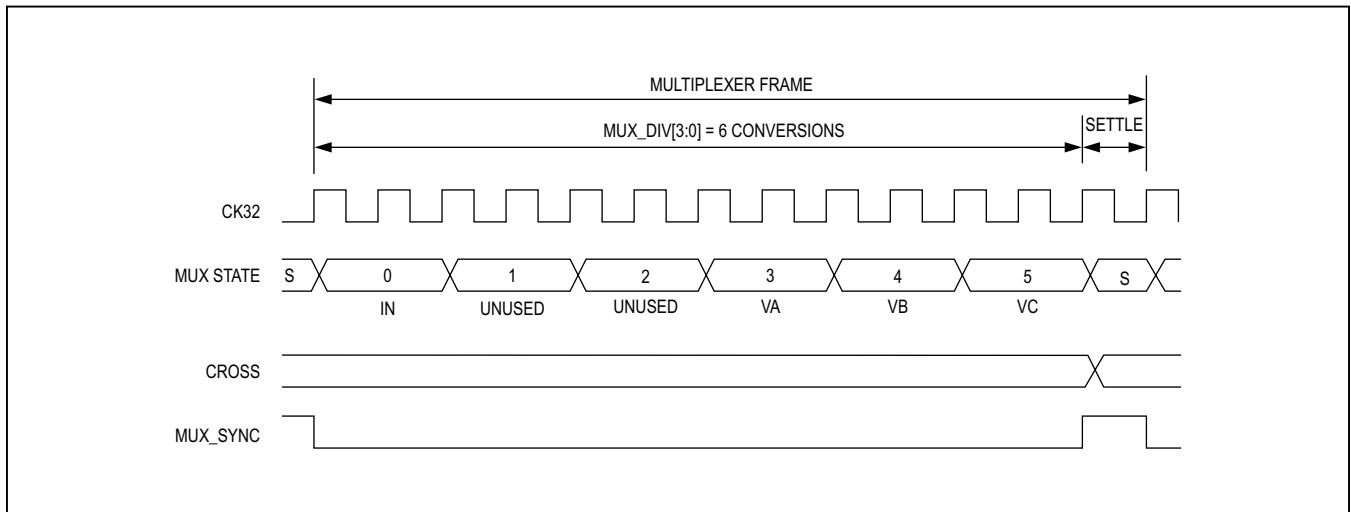


Figure 4. Multiplexer Sequence with Neutral Channel and Remote Sensors

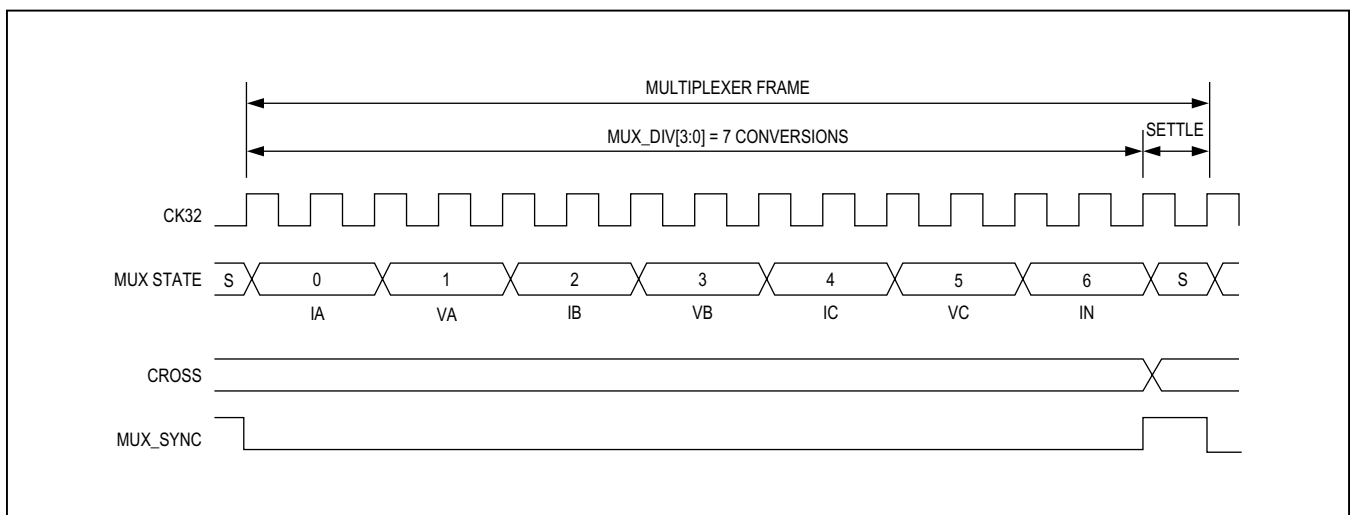


Figure 5. Multiplexer Sequence with Neutral Channel and Current Transformers

Table 1. ADC Input Configuration

PIN	REQUIRED SETTING	COMMENT
IADC0	DIFFx_E = 1	Differential mode must be selected with <i>DIFFx_E</i> = 1. The ADC results are stored in ADC0 and ADC1 is not disturbed.
IADC1		
IADC2	DIFFx_E = 1 or RMT_E = 1	For locally connected sensors the differential input must be enabled.
IADC3		For the remote sensor <i>RMT_E</i> must be set. ADC results are stored in <i>ADC2</i> and <i>ADC3</i> is not disturbed.
IADC4	DIFFx_E = 1 or RMT_E = 1	For locally connected sensors the differential input must be enabled.
IADC5		For the remote sensor <i>RMT_E</i> must be set. ADC results are stored in <i>ADC4</i> and <i>ADC5</i> is not disturbed.
IADC6	DIFFx_E = 1 or RMT_E = 1	For locally connected sensors the differential input must be enabled.
IADC7		For the remote sensor <i>RMT_E</i> must be set. ADC results are stored in <i>ADC6</i> and <i>ADC7</i> is not disturbed.
VADC8	—	Phase A voltage. Single ended mode only. ADC result stored in ADC8.
VADC9	—	Phase B voltage. Single ended mode only. ADC result stored in ADC9.
VADC10	—	Phase A voltage. Single ended mode only. ADC result stored in ADC10.

The recommended ADC multiplexer sequence samples the current first, immediately followed by sampling of the corresponding phase voltage, thus the voltage is delayed by a phase angle Φ relative to the current. The delay compensation implemented in the CE aligns the voltage samples with their corresponding current samples by first delaying the current samples by one full sample interval (i.e., 360°), then routing the voltage samples through the allpass filter, thus delaying the voltage samples by $360^\circ - \theta$, resulting in the residual phase error between the current and its corresponding voltage of $B - \Phi$. The residual phase error is negligible, and is typically less than ± 1.5 milli-degrees at 100Hz, thus it does not contribute to errors in the energy measurements.

When using remote sensors, the CE performs the same delay compensation described above to align each voltage sample with its corresponding current sample. Even though the remote current samples do not pass through the 71M654xT multiplexer, their timing relationship to their corresponding voltages is fixed and precisely known.

ADC Preampifier

The ADC preampifier is a low-noise differential amplifier with a fixed gain of 8 available only on the IADC0-IADC1 sensor input pins. A gain of 8 is enabled by setting *PRE_E* = 1. When disabled, the supply current of the preampifier is < 10 nA and the gain is unity. With proper settings of the *PRE_E* and *DIFFA_E* (I/O RAM 0x210C[4]) bits, the preampifier can be used whether or not differential mode is selected. For best performance, the differential

mode is recommended. In order to save power, the bias current of the preampifier and ADC is adjusted according to the *ADC_DIV* control bit (I/O RAM 0x2200[5]).

Analog-to-Digital Converter (ADC)

A single 2nd-order delta-sigma ADC digitizes the voltage and current inputs to the device. The resolution of the ADC, including the sign bit, is 21 bits (*FIR_LEN*[1:0] = 1), or 22 bits (*FIR_LEN*[1:0] = 2).

Initiation of each ADC conversion is controlled by *MUX_CTRL* internal circuit. At the end of each ADC conversion, the FIR filter output data is stored into the CE RAM location determined by the multiplexer selection. FIR data is stored LSB justified, but shifted left 9 bits.

FIR Filter

The finite impulse response filter is an integral part of the ADC and it is optimized for use with the multiplexer. The purpose of the FIR filter is to decimate the ADC output to the desired resolution. At the end of each ADC conversion, the output data is stored into the fixed CE RAM location determined by the multiplexer selection.

Voltage References

A bandgap circuit provides the reference voltage to the ADC. The *V_{REF}* band-gap amplifier is chopper-stabilized to remove the dc offset voltage. This offset voltage is the most significant long-term drift mechanism in voltage reference circuits.

Isolated Sensor Interface

Nonisolating sensors, such as shunt resistors, can be connected to the inputs of the 71M654xT through a combination of a pulse transformer and a 71M6x03 isolated sensor interface. The 71M6x03 receives power directly from the 71M654xT through a pulse transformer and does not require a dedicated power supply circuit. The 71M6x03 establishes 2-way communication with the 71M654xT, supplying current samples and auxiliary information such as sensor temperature through a serial data stream.

Up to three 71M6x03 isolated sensors can be supported by the 71M6545T/HT. When a remote sensor interface is enabled, the two analog current inputs become reconfigured as a digital remote sensor interface. Each 71M6x03 isolated sensor consists of the following building blocks:

- Power supply for power pulses received from the 71M654xT
- Digital communications interface
- Shunt signal preamplifier
- Delta-sigma ADC converter with precision bandgap reference (chopping amplifier)
- Temperature sensor
- Fuse system containing part-specific information

During an ordinary multiplexer cycle, the 71M654xT internally determines which other channels are enabled. At the same time, it decimates the modulator output from the 71M6x03 isolated sensors. Each result is written to CE RAM during one of its CE access time slots.

The ADC of the 71M6x03 derives its timing from the power pulses generated by the 71M654xT and as a result, operates its ADC slaved to the frequency of the power pulses. The generation of power pulses, as well as the communication protocol between the 71M654xT and 71M6x03 isolated sensor is automatic and transparent to the user.

The 71M654xT can read data and status from, and can write control information to the 71M6x03 isolated sensor. With hardware and trim-related information on each connected 71M6x03 isolated sensor available to the 71M6545T/HT, the MPU can implement temperature compensation of the energy measurement based on the individual temperature characteristics of the 71M6x03 isolated sensor.

Digital Computation Engine (CE)

The CE, a dedicated 32-bit signal processor, performs the precision computations necessary to accurately measure energy. The CE calculations and processes include:

- Multiplication of each current sample with its associated voltage sample to obtain the energy per sample (when multiplied with the constant sample time).
- Frequency-insensitive delay cancellation on all four channels (to compensate for the delay between samples caused by the multiplexing scheme).
- 90° phase shifter (for VAR calculations).
- Pulse generation.
- Monitoring of the input signal frequency (for frequency and phase information).
- Monitoring of the input signal amplitude (for sag detection).
- Scaling of the processed samples based on calibration coefficients.
- Scaling of samples based on temperature compensation information.

Meter Equations

The 71M6545T/HT provides hardware assistance to the CE in order to support various meter equations. The compute engine firmware for industrial configurations can implement the equations listed in [Table 2](#). EQU[2:0] specifies the equation to be used based on the meter configuration and on the number of phases used for metering.

Real-Time Monitor

The CE contains a real-time monitor (RTM), which can be programmed to monitor four selectable XRAM locations at full sample rate. The four monitored locations are serially output to the TMUXOUT pin via the digital output multiplexer at the beginning of each CE code pass. The RTM can be enabled and disabled with control bit RTM_E. The RTM output is clocked by CKTEST. Each RTM word is clocked out in 35 CKCE cycles (1 CKCE cycle is equivalent to 203ns) and contains a leading flag bit.

Table 2. Inputs Selected in Multiplexer Cycles

EQU	DESCRIPTION	Wh AND VARh FORMULA			RECOMMENDED MULTIPLEXER SEQUENCE
		ELEMENT 0	ELEMENT 1	ELEMENT 2	
2	2-element, 3W 3ph Delta	VA x IA	VA x IB	N/A	IA VA IB VB
3	2-element, 4W 3ph Delta	VA (IA-IB)/2	VC x IC	N/A	IA VA IB VB IC VC
4	2-element, 4W 3ph Wye	VA (IA-IB)/2	VB (IC-IB)/2	N/A	IA VA IB VB IC VC
5	3-element, 4W 3ph Wye	VA x IA	VB x IA	VC x IC	IA VA IB VB IC VC (ID)

Note: Only EQU = 5 is supported by currently available CE code versions for the 71M6545T/HT. Contact your Maxim Integrated representative for CE codes that support equations 2, 3, and 4.

Pulse Generators

The 71M6545T/HT provides four pulse generators, VPULSE, WPULSE, XPULSE and YPULSE, as well as hardware support for the VPULSE and WPULSE pulse generators. The pulse generators can be used to output CE status indicators (for example, voltage sag) to DIO pins. All pulses can be configured to generate interrupts to the MPU.

The polarity of the pulses may be inverted with control bit PLS_INV. When this bit is set, the pulses are active high, rather than the more usual active low. PLS_INV inverts all four pulse outputs.

The function of each pulse generator is determined by the CE code and the MPU code must configure the corresponding pulse outputs in agreement with the CE code. For example, standard CE code produces a mains zero-crossing pulse on XPULSE and a SAG pulse on YPULSE.

A common use of the zero-crossing pulses is to generate interrupt in order to drive real-time clock software in places where the mains frequency is sufficiently accurate to do so and also to adjust for crystal aging. A common use for the SAG pulse is to generate an interrupt that alerts the MPU when mains power is about to fail, so that the MPU code can store accumulated energy and other data to EEPROM before the V_{V3P3SYS} supply voltage actually drops.

XPULSE and YPULSE

Pulses generated by the CE may be exported to the XPULSE and YPULSE pulse output pins. Pins SEGDI06 and SEGDI07 are used for these pulses, respectively. Generally, the XPULSE and YPULSE outputs can be updated once on each pass of the CE code.

VPULSE and WPULSE

By default, WPULSE emits a pulse proportional to real energy consumed, and VPULSE emits a pulse propor-

tional to reactive energy. During each CE code pass the hardware stores exported WPULSE and VPULSE sign bits in an 8-bit FIFO and sends the buffered sign bits to the output pin at a specified, known interval. This permits the CE code to calculate the VPULSE and WPULSE outputs at the beginning of its code pass and to rely on hardware to spread them over the multiplexer frame.

80515 MPU Core

The 71M6545T/HT includes an 80515 MPU (8-bit, 8051-compatible) that processes most instructions in one clock cycle: a 4.9MHz clock results in a processing throughput of 4.9 MIPS. The 80515 architecture eliminates redundant bus states and implements parallel execution of fetch and execution phases. Normally, a machine cycle is aligned with a memory fetch, therefore, most of the 1-byte instructions are performed in a single machine cycle (MPU clock cycle). This leads to an 8x average performance improvement (in terms of MIPS) over the 8051 device running at the same clock frequency.

The CKMPU frequency is a function of the MCK clock (19.6608MHz) divided by the MPU clock divider which is set in the I/O RAM control field MPU_DIV[2:0]. Actual processor clocking speed can be adjusted to the total processing demand of the application (metering calculations, AMR management, memory management, and I/O management) using MPU_DIV[2:0], as shown in [Table 3](#).

Memory Organization and Addressing

The 80515 MPU core incorporates the Harvard architecture with separate code and data spaces. Memory organization in the 80515 is similar to that of the industry standard 8051. There are three memory areas: program memory (flash, shared by MPU and CE), external RAM (data RAM, shared by the CE and MPU, configuration or I/O RAM), and internal data memory (internal RAM).